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O-Leading PCB, PCB PCB PCB (PCBA) EMS PCB HDI PCB, PCB, PCB PCB PCB. PCB PCB PCB PCB PCB.

PCB PCB PCB, PCB PCB PCB PCB PCB. PCB PCB PCB PCB PCB O PCB PCB.

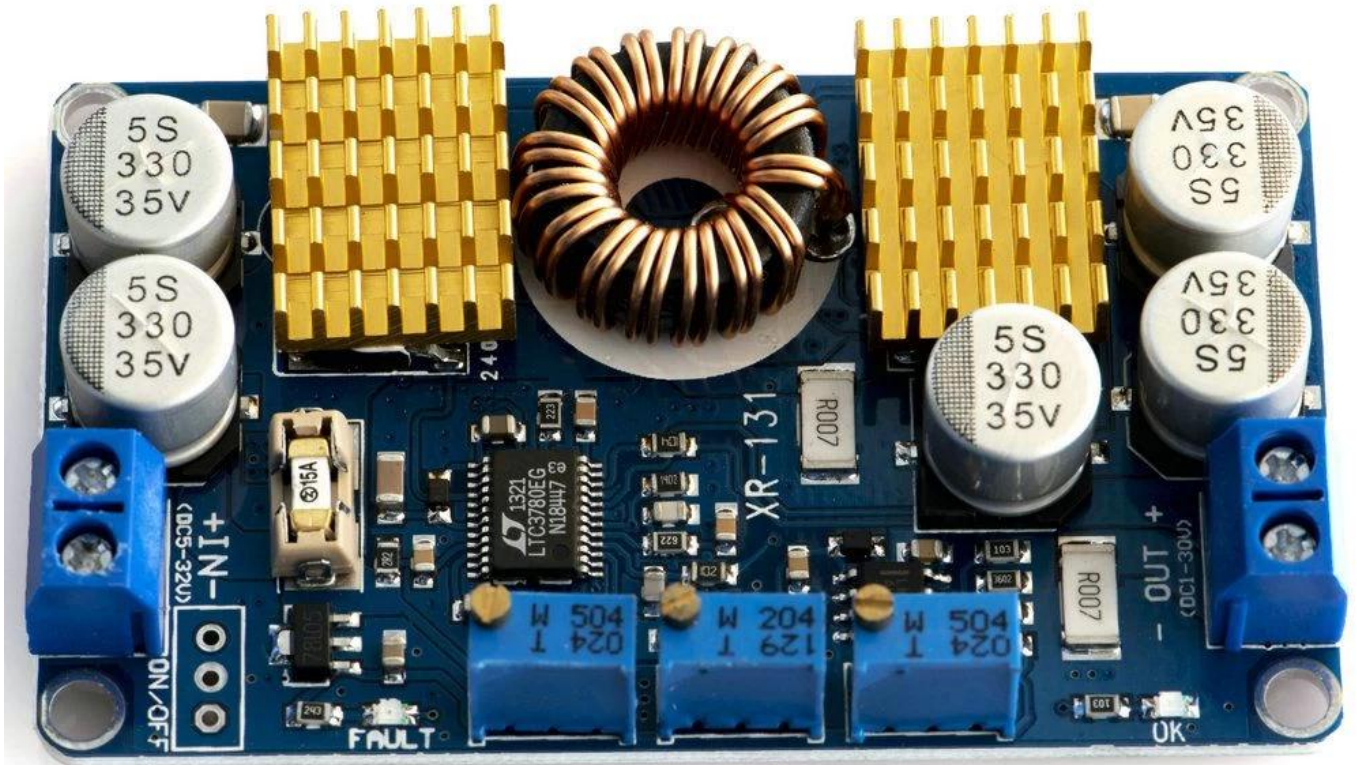
PCB O-leading PCB PCB PCB PCB PCB, PCB PCB PCB PCB PCB PCB PCB PCB PCB PCB PCB PCB.

PCB PCB PCB PCB. [PCB PCB PCB PCB PCB](#)

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78 x 46.5 x 15mm (PCB PCB PCB)

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PCB PCB PCB PCB PCB PCB PCB PCB PCB PCB PCB, PCB PCB PCB PCB PCB.



3B 4B □□□□□□□□

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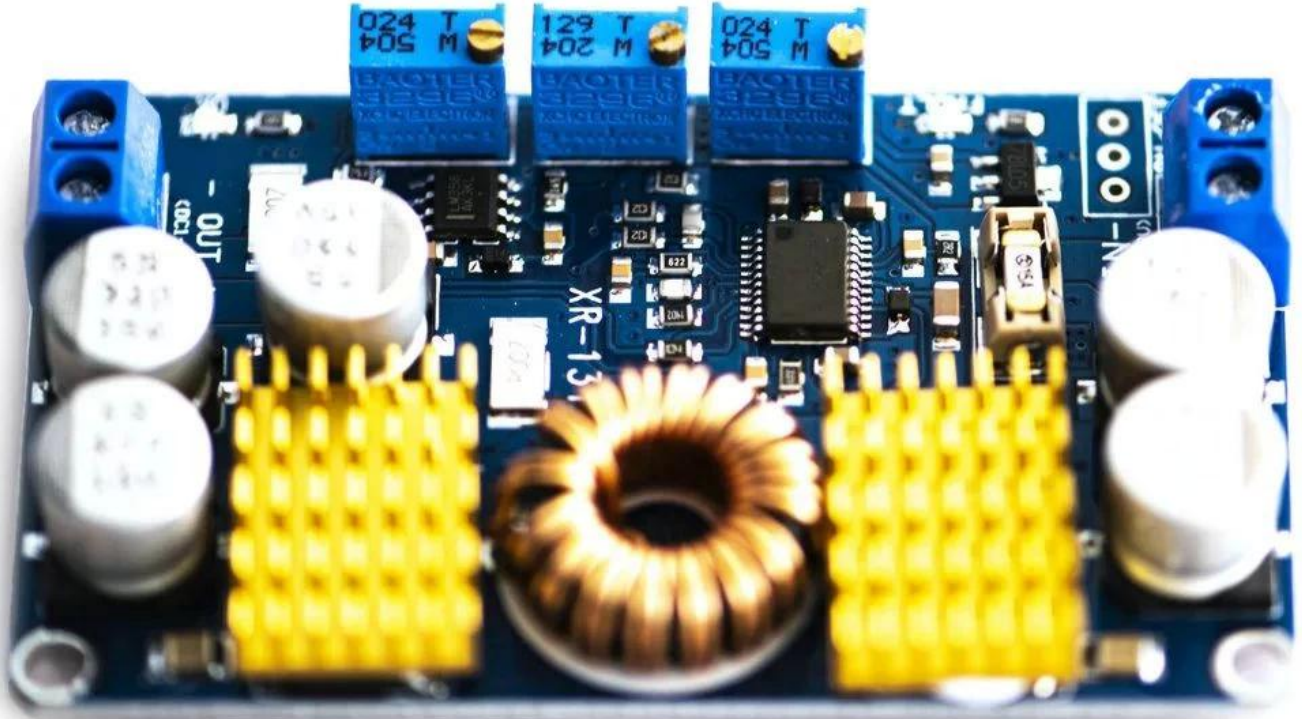
□□ □□ :	DC5-32V
□□ □□ :	DC1V-30V □□ □□ □□
□□ □□:	8A, 10A □□ □ □ □□
□□ □□:	□□ 80W, □□ □ 130W, 80W □ □□□□□ □ □□ □□;
□□ □□ :	50mV

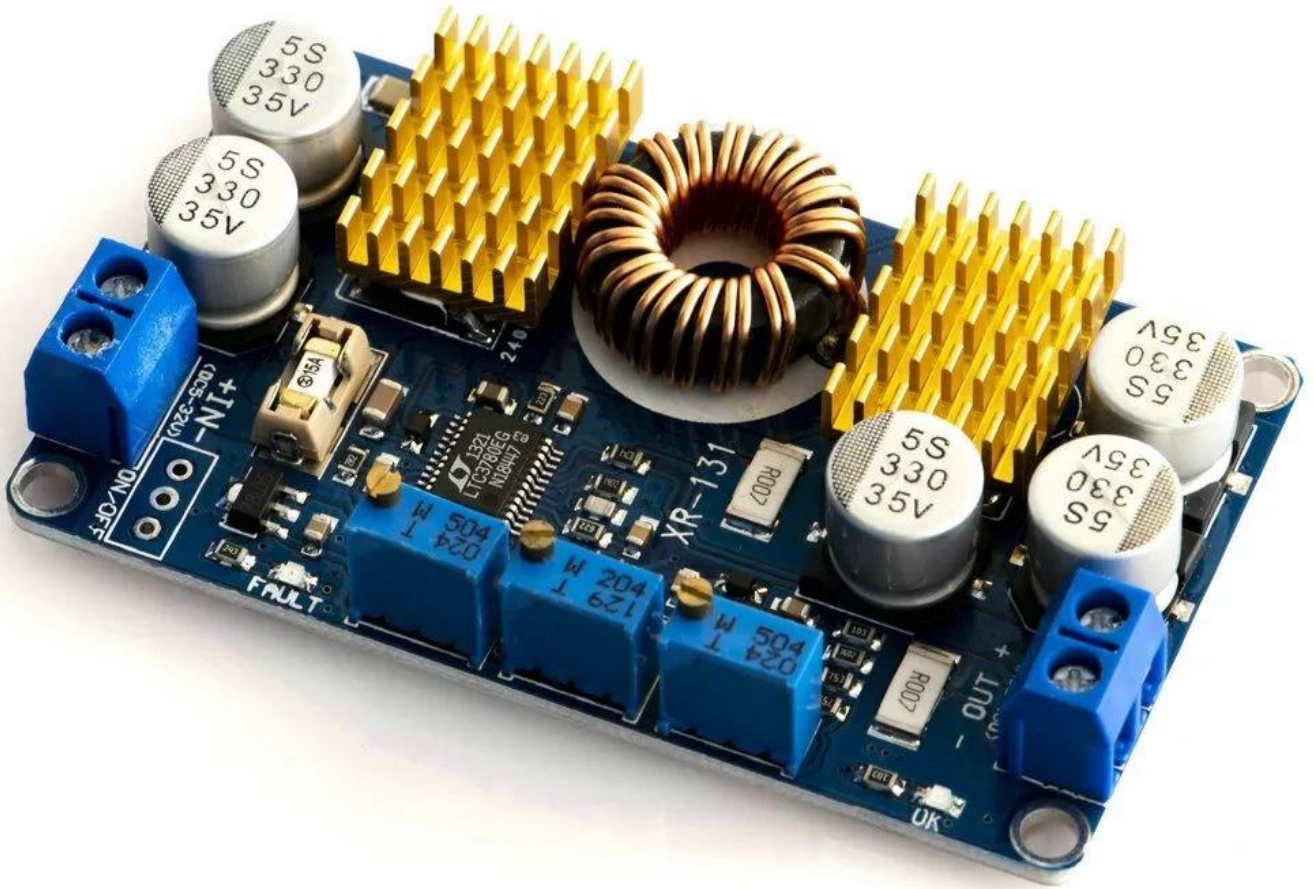
□□ □□ □□ :

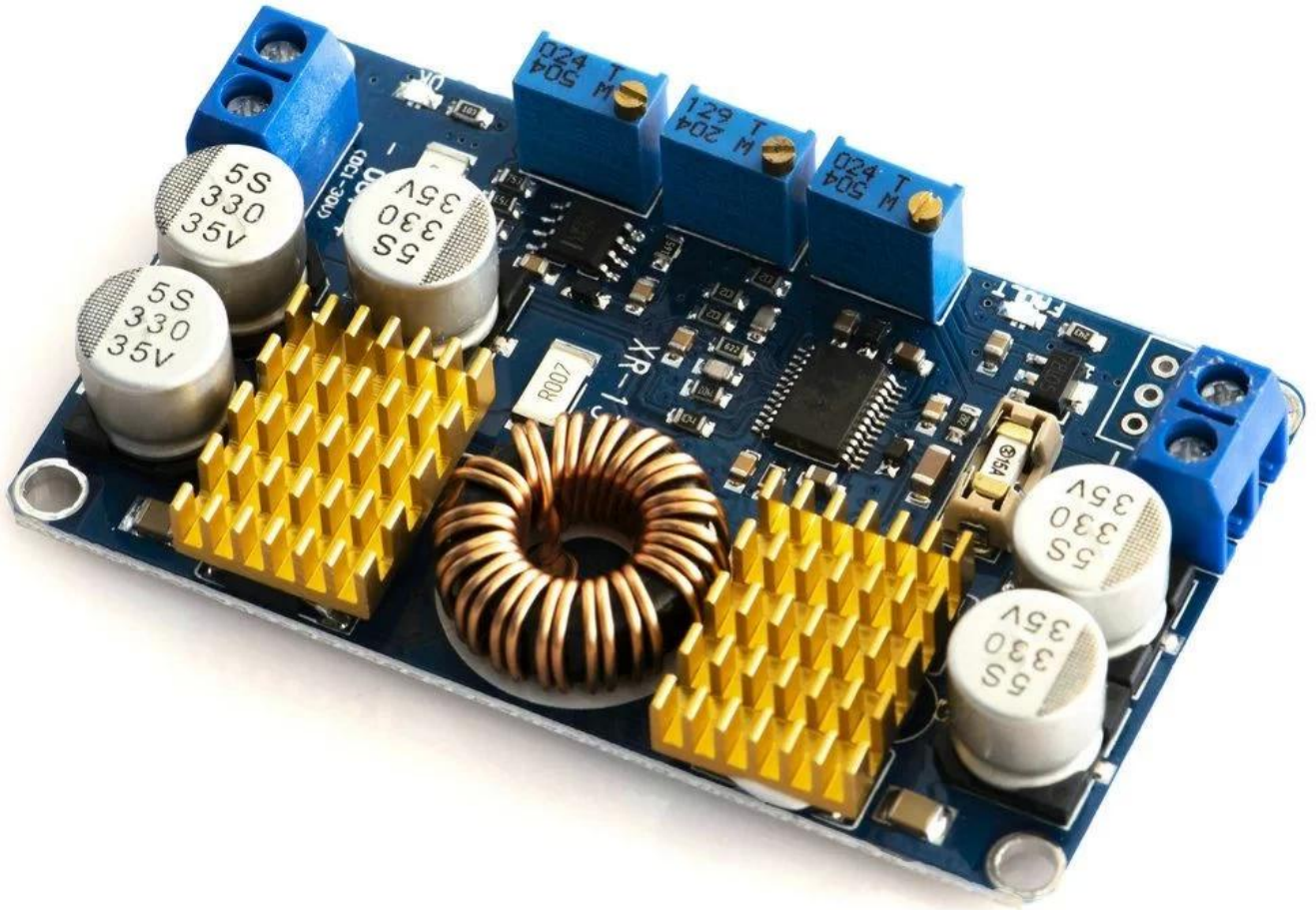
-45 ~ + 85

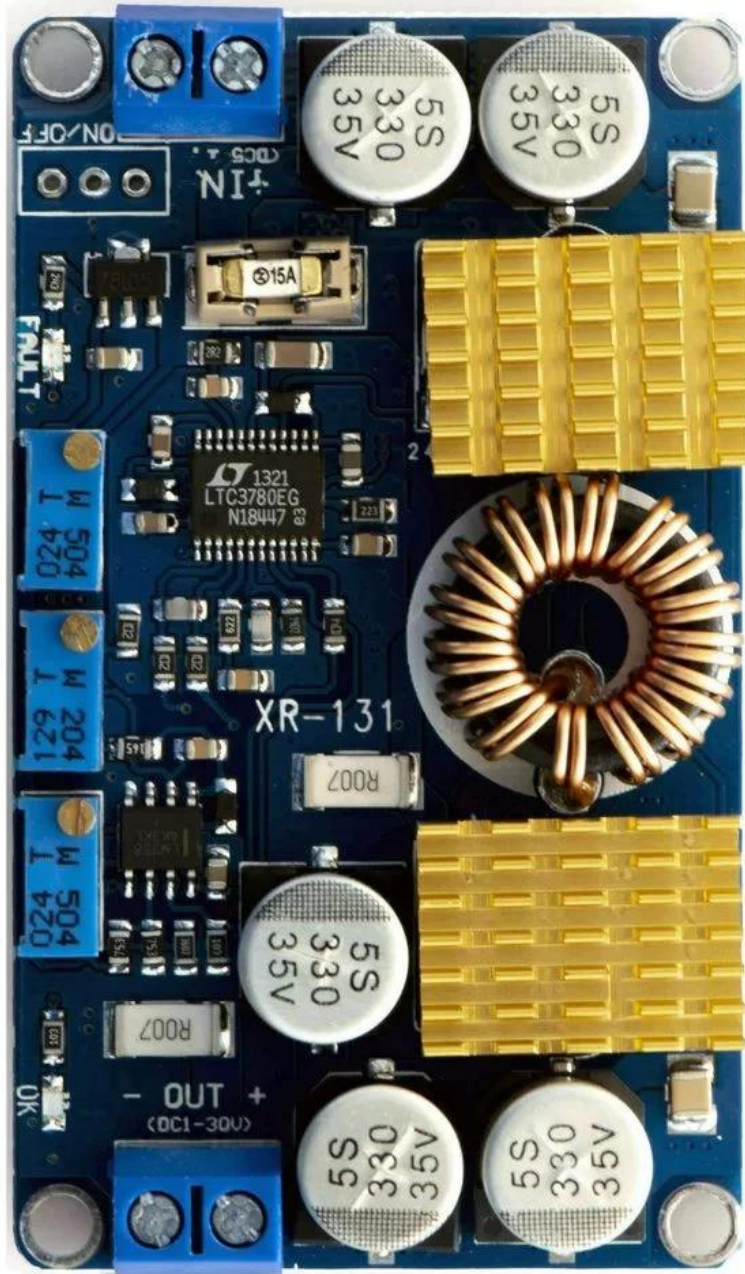


O-LEADING
To Be Reliable, To Be Valuable









X
X
X
X





Factory PCB



Automatic vacuum press machine



Drilling Machine



Pattern Plating Machine



Scrubbing Machine



Developing Machine



Routing Machine



High-speed flying probe machine



E-test Machine

Factory SMT





CICC INSPECTION CERTIFICATION



嘉泰认证

QUALITY MANAGEMENT SYSTEM CERTIFICATE

Certificate No: 18118Q10347R05

We hereby certify that

O-LEADING SUPPLY CHAIN(HK) CO.,LIMITED

Credit No: 61691591-000-07-18-7

Registration Add: FLAT/RM 1205 12/F TAI SANG BANK BUILDING 130-132 DES VOEUS ROAD CENTRAL HK

Business Add: 1313, Floor 13, Fortune Building, Danshui Town, Huiyang District, Huizhou, Guangdong, China

Has implemented and maintains a **Quality Management System** Which fulfils the requirements of the following standards
GB/T19001-2016 idt ISO9001:2015

Scope of certification
Sales of printed circuit boards

Initial issuance period: February 27, 2018
Renewal date: April 22, 2019
This certificate is valid during: April 22, 2019 ~ February 26, 2021
This certificate is invalid without CICC qualified label in the following period

First supervision and audit	Second supervision and audit	Qualified mark
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The certification implications are under client's control. These production processes which fall to be covered by the relevant effective administrative provisions and qualification provisions regulated by the state. The effectiveness of this certificate shall be notified by annual surveillance audit of CICC. The certificate shall be valid when used together with the surveillance audit certificate. The initial issuance of this certificate can be searched at the portal of CICC: www.cicc.com.cn or by the code of inquiry: www.cicc.com.cn






CICC INSPECTION CERTIFICATION



嘉泰认证

质量管理体系认证证书

证书号: 18118Q10347R05

兹证明

诚领供应链(香港)有限公司

统一社会信用代码: 61691591-000-07-18-7
注册地址: 香港中環德輔道中 130-132 號大生銀行大廈 1205 室
经营地址: 广东惠州惠阳淡水南亨西路财富大厦 13 楼 1313


建立的质量管理体系符合
GB/T19001-2016 idt ISO9001:2015 质量标准适用条款的要求


认证范围
印刷线路板的销售

初次发证日期: 2018年02月27日
换证日期: 2019年04月22日
证书有效期: 自2019年04月22日至2021年02月26日
在下列期限内, 未经 CICC 黏贴合格标贴, 本证书无效

第一次复审	第二次复审	粘标处
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本证书认证范围不包括未获得有效的国家规定的行政许可、资质许可的产品/服务范围。本证书通过CICC定期监督审核保持, 与年度《保持认证通知书》共同方为有效。本证书信息可在国家认监委网站: www.cma.gov.cn及CICC网站www.cicc.com.cn查询。





Test Report

No. SZXEC1900530401 Date: 30 Mar 2019 Page 1 of 6

O-LEADING SUPPLY CHAIN (HK) CO., LIMITED

1313.FLOOR 13, FORTUNE BUILDING, DANSHUI TOWN, HUIYANG DISTRICT, HUIZHOU, GUANGDONG, CHINA

The following sample(s) was/were submitted and identified on behalf of the clients as : OSP

SGS Job No. : RP19-005089 - SZ
Date of Sample Received : 22 Mar 2019
Testing Period : 22 Mar 2019 - 30 Mar 2019
Test Requested : Selected test(s) as requested by client.
Test Method : Please refer to next page(s).
Test Results : Please refer to next page(s).

Conclusion : Based on the performed tests on submitted sample(s), the results of Lead, Mercury, Cadmium, Hexavalent chromium, Polybrominated biphenyls (PBBs), Polybrominated diphenyl ethers (PBDEs) and Phthalates such as Bis(2-ethylhexyl) phthalate (DEHP) , Butyl benzyl phthalate (BBP), Dibutyl phthalate (DBP) , and Diisobutyl phthalate (DIBP) comply with the limits as set by RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU.

Signed for and on behalf of
SGS-CSTC Standards Technical Services Co., Ltd. Shenzhen Branch

Tina
Tina Fan
Approved Signatory



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Test Report

No. SZXEC1900530401 Date: 30 Mar 2019 Page 2 of 6

Test Results :

Test Part Description :

Table with 3 columns: Specimen No., SGS Sample ID, Description. Row 1: SN1, SZX19-005304.001, Green"PCB"

Remarks :

- (1) 1 mg/kg = 1 ppm = 0.0001%
(2) MDL = Method Detection Limit
(3) ND = Not Detected (< MDL)
(4) "-" = Not Regulated

RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU

Test Method : With reference to IEC 62321-4:2013+A1:2017, IEC 62321-5:2013, IEC 62321-7-2:2017, IEC 62321-6:2015 and IEC 62321-8:2017, analyzed by ICP-OES, UV-Vis and GC-MS.

Table with 5 columns: Test Item(s), Limit, Unit, MDL, 0/1. Lists various substances like Cadmium, Lead, Mercury, Hexavalent Chromium, and various brominated biphenyls with their respective limits and detection results.



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Member of the SGS Group (SGS SA)



ZPMV2.E490354 - WIRING, PRINTED - COMPONENT

Wiring, Printed - Component

See General Information for Wiring, Printed - Component

O-LEADING SUPPLY CHAIN (HK) CO LTD
 ROOM 1205, 12/F
 TAI SANG BANK BLDG
 130-132 DES VOEUS ROAD
 CENTRAL, HONG KONG

E490354

Type	Cond Width		Cond Thk	SS/ DS/ DSO	Max	Max		Meets	C			
	Min	Edge			Area	Solder	Oper			Flame		
	mm(in)	mm(in)	mic(mil)		mm(in)	C	sec	C	Class	UL796	DSR	I
Multilayer (mass laminate) printed wiring boards.												
O-LEADING-401	0.1 (0.004)	0.3 (0.012)	34 (1.34)	DS	12.7 (0.5)	260	10	130	V-0	-	-	
O-LEADING-407	0.08 (0.003)	0.2 (0.008)	17 (0.67)	DS	9.7 (0.4)	260	10	130	V-0	All	-	
Multilayer printed wiring boards.												
O-LEADING-408	0.125 (0.005)	0.125 (0.005)	12 (0.47) Int:136	DS	50.8 (2.0)	280	20	130	V-0	All	*	
Single layer printed wiring boards.												
O-LEADING-002	0.38 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	105	V-0	All	-	
O-LEADING-003	0.38 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	130	V-0	▲	-	
O-LEADING-033	0.15 (0.006)	0.3 (0.012)	34 (1.34)	SS	25.4 (1.0)	260	10	120	V-0	All	-	
O-LEADING-205	0.1 (0.004)	0.3 (0.012)	34 (1.34)	DS	69.6 (2.7)	260	10	130	V-0	All	-	
O-LEADING-206	0.15 (0.006)	0.33 (0.013)	17 (0.67)	DS	69.6 (2.7)	260	10	130	V-0	All	-	
O-LEADING-D01	0.14 (0.006)	0.15 (0.006)	33 (1.30)	DS	25.4 (1.0)	260	10	130	V-0	All	*	
O-LEADING-S01	0.25 (0.010)	0.25 (0.010)	17 (0.67)	SS	25.4 (1.0)	260	4	130	V-0	All	*	

WIRING, PRINTED - COMPONENT | UL Product iQ

O-LEADING-S02	0.2 (0.008)	0.2 (0.008)	17 (0.67)	SS	25.4 (1.0)	260	4	130	HB	▲	*	
O-LEADING-S03	0.25 (0.010)	0.25 (0.010)	34 (1.34)	SS	25.4 (1.0)	260	4	130	V-0	All	*	

* - CTI marking is optional and may be marked on the printed wiring board.

Marking: Company name or file number and type designation. May be followed by a suffix to denote factory identification or burning test classification.

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PCB

PCB	
Layer Count	1-32
Weight	1 / 3oz-12oz
Min. Thickness / Max. Thickness	3.0mil / 3.0mil
Min. Thickness / Max. Thickness	4.0mil / 4.0mil
Aspect Ratio	10 : 1
Min. Drill	0.2mm-5.0mm
Min. Drill (Micro)	635 * 1500mm
Min. Drill (Micro)	4mil
Plated Through Hole	+/- 3mil
Blind / Buried Vias (All)	Yes
Min. Drill (Micro)	Yes
Material	FR-4, FR-4high Tg, Epoxy, Polyimide, Copper, Aluminum
Surface Finish	HASL, OSP, ENIG, HAL-LF, Immersion Silver, Electroless Nickel

SMT

PCB Material	FR-4, CEM-1, CEM-3, Epoxy, Polyimide
PCB Size	510x460mm
PCB Size	50x50mm
PCB Thickness	0.5mm-4.5mm
Min. Drill	0.5-4mm
Min. Drill (Micro)	0201
Min. Drill (Micro)	0603
Min. Drill (Micro)	15mm
Min. Drill (Micro)	0.3mm
Min. Drill (Micro)	0.4mm
Min. Drill (Micro)	+/- 0.03mm

PCB

Shipping service



Quick Turn Lead Time		
Layer Count:	Lead Tim	Special Requirement
1L/2L	2-3days	24 Hours,48 Hours
4L	3-4days	48 Hours
6L	4-5days	72 Hours
8L	5-6days	NA
10L	6-7days	NA
12L	7-8days	NA
14L	8-9days	NA

Standard Lead Time		
Layer Count:	Sample Lead Time	Volume order lead time
2L	4 days	10 days
4L	5 days	11 days
6L	6 days	12 days
8L	8 days	14 days
10L	10 days	16 days
12L	12 days	18 days
14L	14 days	20 days
16-32L	18 days	24 days

O-LEADING

1. O-Leading 100% 100% 100%?

100% 100% 100% 100% 100%.

1.1 100% ISO 9001 : 2008 100% 100% 100%.

1.2 100% 100% 100% 100% 100%

1.3 100% 100% 100% 100% : 100% 100%, X-ray 100%, AOI (Automated Optical Inspector) 100% ICT (in-circuit testing).

1.4 100% 100% 100% 100% 100% 100%

1.5. 100% 100% 100%

2. O-Leading 100% 100% 100%?

100% 100% 100% (100% : 100%, 100% 100%) 100% 100%, 100% 100% 100% 100%. 100% 100% 100% 100% 31% 100%. 100% 100% 100%.

100% O-Leading 100% 100% 100%. 100% 100%, 100% 100% 100% 100% 100% 100%. 100% 100% 100% 100% 100% 100% 100% 100%.

100% 100% 100% 100%. 100% 100% 100% 100% 100% 100% 100% 100% 100% 100% 100%.

3. O-Leading 100% 100% 100% 100%?

100% FR4, 100% TG 100% 100% 100%, Rogers, Arlon, Telfon, 100% / 100% 100%, PI 100%

4. PCB 及 PCBA 的製造過程是什麼?

- 4.1 物料清單 BOM (Bill of Materials) : 物料清單, 物料清單表 及 物料清單.
- 4.2 PCB Gerber 檔.
- 4.3 PCB 的製造及 PCBA 的製造.
- 4.4 物料清單.
- 4.5 物料清單 及 物料清單 的製造過程.

5. PCB 的製造過程是什麼?

物料清單 → 物料清單表 → 物料清單 → PCB AOI → 物料清單 → 物料清單 → PTH → 物料清單 → 物料清單 → 物料清單 → 物料清單 → PCB AOI → 物料清單 → 物料清單 → 物料清單 → 物料清單 → E / T → 物料清單.

6. HDI 的製造過程是什麼?

物料清單 物料清單 : 物料清單, VCP 物料, 物料清單, LDI 物料清單 物料清單 物料清單, 物料清單 Mitsubishi Hitachi, LDI 物料 Screen (Japan), 物料清單 Hitachi 物料清單, 物料清單 物料清單 物料清單 物料清單.

7. O-lead 的製造過程是什麼?

O-lead 物料 ENIG, OSP, LF-HASL, 物料 (物料 / 物料), 物料, 物料, 物料 物料, 物料 物料 物料 物料 物料 物料 物料. HDI 物料 物料 物料 OSP, ENIG, OSP + ENIG, BGA PAD 物料 0.3 mm 物料 物料 物料 物料 OSP OSP + ENIG 物料 物料 物料.

8. FPC 的製造過程是什麼? O-Leading 及 SMT 的製造過程是什麼?

O-Leading 物料 物料 物料 FPC 物料 物料, 物料 物料 2000mm * 240mm 物料. 物料 物料 "Flex Capability" 物料 物料. 物料 物料 SMT 物料 物料 物料.

9. PCB 的製造過程是什麼?

- 物料;
- 物料 物料;
- 物料 物料;
- 物料 物料 物料;
- PCB 物料;
- 物料 物料;
- 物料 物料 物料.

10. PCB, PWB 及 FPC 的製造過程是什麼?

PCB 物料 物料 物料 物料.
PWB 物料 物料 物料 物料 物料 物料 物料.
FPC Flexible Printed Board 物料.

11. PCB 的製造過程是什麼?

PCB 物料 物料 物料 物料 物料.
物料 Tg 物料 物料 物料.
物料 CTE 物料 物料 物料 物料 物料;
物料 物料 物料 : 物料 PCB 物料 50 物料 250 °C 物料.
物料 物料; 物料 物料 物料 物料 / 物料 物料 物料 PCB 物料. 物料 PCB 物料 物料 物料 物料 物料; 物料 物料 物料 物料 物料 物料 物料.

12. O-leading 的 PCB 的製造過程是什麼?

O-leading 物料 物料 PCB FPC PCB 物料 物料 物料 物料 物料 物料. 物料 物料 物料 物料 物料 物料 物料 物料 物料 物料 物料 物料.

13. 物料 物料 物料 物料?

□□□□ □□ □□□□ □□ □□□ □□, SI6000 soft □ POLAR INSTRUMENTS□ CITS 500s □□□ □□□□ □□□□□.
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